JSCJ

MSDS Report

Report NO.: M000004000312

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	BSS138
Package Type :	SOT-23

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total	
				A	B
Wafer	Silicon	7440-21-3	100.00%	0.61%	0.57%
Lead Frame-A	Copper	7440-50-8	2.00%	23.72%	27.65%
	Iron	7439-89-6	55.00%		
	Nickel	7440-02-0	41.40%		
	Manganese	7439-96-5	0.80%		
	Silicon	7440-21-3	0.30%		
	Carbon	7440-44-0	0.05%		
	Aluminum	7429-90-5	0.10%		
	Chromium	7440-47-3	0.10%		
	Cobalt	7440-48-4	0.20%		
	Phosphorus	7723-14-0	0.03%		
	Sulphur	7704-34-9	0.03%		
Lead Frame-B (Optional)	Iron(Fe)	7439-89-6	0.06%		
	Nickel(Ni)	7440-02-0	0.90%		
	Copper（Cu）	7440-50-8	95.35%		
	Stannum (Sn)	7440-31-5	2.00%		
	Phosphorus(P)	7723-14-0	0.09%		
	Zinc（Zn）	7440-66-6	0.80%		
	Silver(Ag)	7440-22-4	0.80%		
Wire	Copper	7440-50-8	98.00%	0.11%	0.11%
	Other	/	2.00%		
Mold Compound	Silica	60676-86-0	85.50%	73.56%	69.77%
	Epoxy Resin	29690-82-2	6.00%		
	Phenol Resin	Trade secret	5.50%		
	Fire Retardant	Trade secret	2.50%		
	Carbon black	1333-86-4	0.50%		
Plating	Tin	7440-31-5	99.99%	2.00%	1.90%
	Other	/	0.01%		

NOTE: weight total “A” for Lead Frame-A，”B” for Lead Frame-B (Optional).

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